Technical Data Sheet

1、Application

1.1 This Data Sheet is for Leaded Product and suitable for any constituent and wire diameter with same alloy.

1.2 This Product suitable for high requirement of environmental protection for Manual or automatic Soldering. This product make from Fresh Raw Materials and Professional allocate. It has a widely used in environment friendly Electronics Industry. Product Standard is: GB/T 20422-2006.

2、Product Information

2.1 Name: Solder Wire

2.2 Model: ПОС 63 Flux

2.3 Chemistry Expression: Sn63/Pb37

2.4 Product Shape: Filaments

2.5 Customer's Requirements

Diameter，mm	0.30 mm	0.60 mm	0.80 mm	1.00 mm	1.20 mm	1.60 mm	1.80 mm	2.00 mm
Requirement								
Flux，%	1.40%	1.60%	1.80%	2.00%	2.20%	2.60%	2.80%	3.00%
Requirement								
Flux Type	R Type	RMA Type	RA Type	No Clean	Water Soluble	Aluminum Soldering		
Requirement								

2.6 Diameter Allowed Deviation (mm)

Diameter，mm	≤0.3	0.3~0.8	>0.80~2.5	>2.5~6.0	
Allowed Deviation	±0.02	±0.03	±0.05	±0.1	

Special Size is available

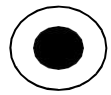
3、Chemical Component

Item	Chemical Component，%								
	Sn	Pb	Sb	AS	Bi	Ag	Fe	Al	Cd
Sn63Pb37	All the Rest	37±0.5	< 0.10	< 0.030	< 0.10	< 0.10	< 0.02	< 0.001	< 0.010

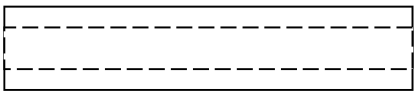
4、Raw Materials Standard

4.1 Product Out Look Long and round Shape with medium altitude, inside Flux

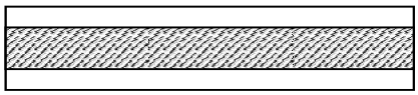
4.2 Structure Picture



Front View



Left View



Cross-section View

5、Materials Physical Characteristics and Testing Way.

5.1 Materials Characteristics

Specification	Melting Point(℃)	Proportion g/cm^3	Tensile Strength Mpa	Electrical Resistivity 10^{-9}ohm.m
Sn63Pb37	183	8.3	32	100~150

5.2 Composition of the Alloy
Data is in the Table.

Item	Chemical Component，%							
	Element	**Sn**	**Ag**	**Cu**	**Al**	**As**	**Cd**	**Fe**
Solder Wire Sn63Pb37	%	All the Rest	0.0025	0.05	<0.0001	<0.0025	<0.0002	0.0005
	Element	**Pb**	**P**	**Bi**	**S**	**Sb**	**Zn**	
	%	37±0.5	<0.0015	0.012	<0.0015	0.0068	<0.0002	

5.3 Flux Characteristics

Items	Standard	Testing Way
Dryness	Surface no adhesive force，Easy to clean out	JIS Z 3197-86
Copper Corrosion	No Corrosion	JIS Z 3197-86
Aqueous Resistance Ω·cm	> 10^5 Ω·cm	JIS Z 3197-86
Surface Insulation Resistance	> 1.0×10^8 Ω	JIS Z 3197-86
Rate of Spread，%	> 80%	JIS Z 3197-86

6、Packing Way

6.1 Roll Mark

6.1.1 Front Mark. Each Roll will mark Chemistry Expression and wire diameter

6.1.2 Back Mark None

6.2 Weight Constitute.

	kg/Roll						kg/box (Net Weight)						Deviation， g	
10 Roller	0.75	0.80	0.85	0.90	1.00		7.50	8.00	8.50	9.00	10.0		Each Roll	±30 g
													Each Box	±100 g

7、 Preservation Way and Time

7.1 Preservation Condition: Room TEMP. 25℃±2℃ ， relative humidity ≤50%RH.

7.2 Preservation Way: Avoid to keep in floor directly.

7.3 Preservation Time: Suggest to use within 180 days after production.

7.4 Attention for Preservation: Sealed container package, storage in dry place. Touch with acid medium or high humidity will make the Alloy lost the metal luster.

7.5 Product Manage: While heating need to avoid in draft metal steam. While Cutting and polishing, need to avoid in draft dust. Do not touch with Eye, Close and make sure the using place has good ventilation environment.

8、 Quality Insurance

8.1 Quality Insurance Procedures,,

Raw Materials testing→melt the Tin Component Testing3→injection molding Testing Out-look Testing3→oil pressure Checking→draw bench Checking→wire wrapping Checking→Package Checking →finished product Checking→Spot Checking

8.2 Customer Complaint Process Mode,,

Complaint→Seller→Quality Inspection Dep.→Solution→Seller→Customer

8.3 Quality Certificate

8.3.1 SGS Report

8.3.2 RoHS Declare

9、 Regulation Documents

9.1 The product fits EU RoHS instructions and China's Environment protecting laws.

9.2 If products have changed, the documents will be updated.

10、 Product Characteristics and Security

10.1 Product Feature

10.1.1 Environment Product, non-pollution: Good fluidity, Solder Point Full, shiny and bright.

10.1.2 Fast Tin Soldering， Suitable for Complicated Printed Circuit Board.

10.1.3 Improve Production efficiency, lower production cost.

10.2 Security Solder Wire normally were used with Flux, it will make some smog. This smog should be pump out and suggest worker to wear protective tools.

10.3 Residue Process: Whether to clean the Solder Point, it based on the Solder Flux using condition and suggest to use with cleaner.

11. Statements

In this document, except some data with allowed tolerance range, other data will conform to Industry allowed tolerance range.